



		Subclas	ISSUE CLASSIFICATION
		Class	

U.S. UTILITY Patent Application

O.I.P.E.	PATENT DATE
	
SCANNED <u>11Km 4</u> Q.A. <u>11/4</u>	

APPLICATION NO.	CONT/PRIOR	CLASS	SUBCLASS	ART UNIT	EXAMINER
09/941360	D	205		1741	42

CONTRIBUTORS

A Method and apparatus for plating and polishing a semiconductor substrate

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PTO-2040
12/89

ISSUING CLASSIFICATION

TERMINAL DISCLAIMER	DRAWINGS			CLAIMS ALLOWED	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.
<input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed.				NOTICE OF ALLOWANCE MAILED	
	(Assistant Examiner)				
<input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S Patent. No. _____				ISSUE FEE	
	(Primary Examiner)			Amount Due	Date Paid
<input type="checkbox"/> The terminal _____ months of this patent have been disclaimed.				ISSUE BATCH NUMBER	
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